

KB 6168 and KB 6068

High Tg, high Td FR-4 Resin System

Kingboard KB 6168 is a resin system designed to meet high Tg and high Td needs for lead free assembly requirements. In today's demanding economic conditions where reliable economical material requirements are a necessity without compromising performance, KB 6168 is the perfect choice.

Material Handling and Storage

KB 6168 laminate can be handled and stored similar to all other FR4 materials. Laminate should be stored covered in a cool location and kept away from moisture. Standard handling practices during processing apply.

KB 6068 prepreg should be stored in a temperature controlled environment: Temp. - 68° F +/- 2° F and 50% +/- 5% RH. For longer shelf life, prepreg may be stored at 36° F +/- 2° F.

Laminate Surface Preparation

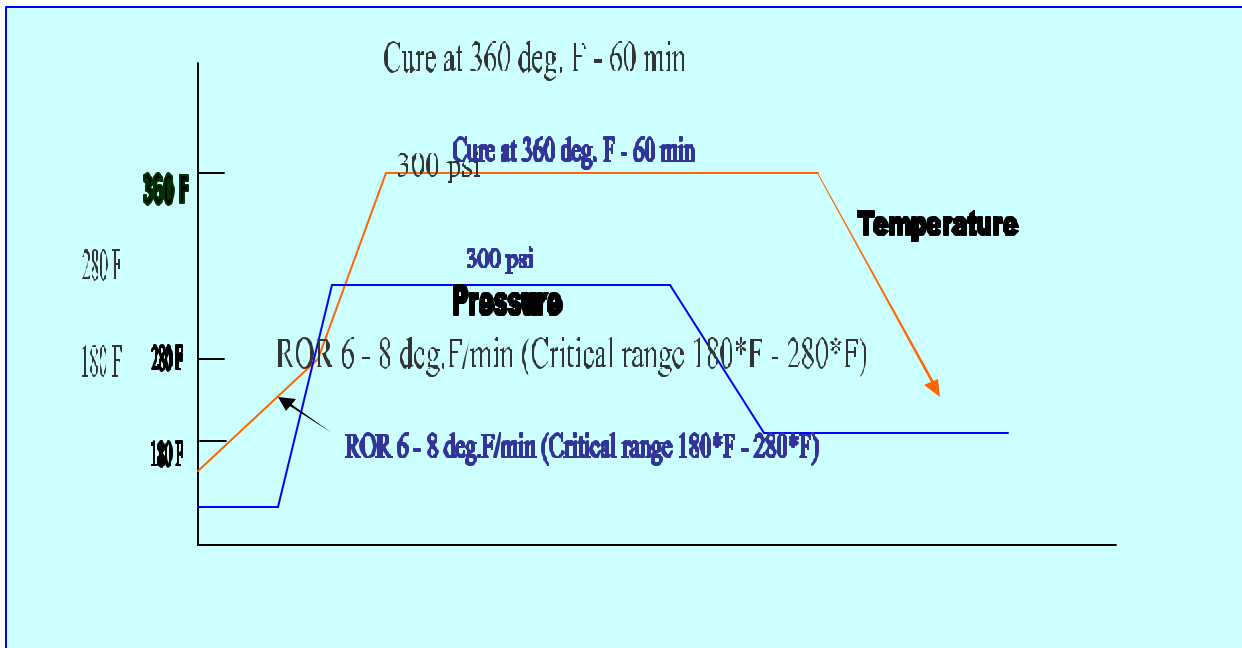
RTF copper cores can be pre-cleaned using standard industry chemical cleaners. Regular shiny copper (on heavier cores) may be cleaned by mechanical or chemical methods.

Inner Layer Treatment / Preparation for Lamination

All industry standard bond enhancement treatments are acceptable. Unless processed in a horizontal conveyerized system with adequate drying capability, bake all cores at 220°F for 20 minutes in racks.

Recommended Lamination Guidelines

- Critical heat ramp up rate between 180°F and 280°F - 6°F to 8°F per minute
- Minimum cure time - 360°F for 60 min (product temperature)
- Full curing pressure at 300 psi in a vacuum hydraulic press
- Maintain pressure during cooling at 140 psi until temp. drops below 320°F



Further Processing:

KB 6168 processes like all equivalent multifunctional filled epoxy FR4 high Tg materials chemical hole wall preparation, drilling, routing and scoring.